REMARKS

INTRODUCTION

In accordance with the foregoing, claims 1, 2 and 5 have been amended. Claims 11 and 13 have been cancelled. Claims 1-5, 10, 12, 14 and 15 are pending and under consideration.

CLAIM REJECTIONS

Claim 1 was rejected under 35 USC 103(a) as being unpatentable over Ito et al. (US 6,410,904) (hereinafter "Ito") in view of the applicant's admitted prior art (hereinafter "AAPA").

Claims 2-4 were rejected under 35 USC 103(a) as being unpatentable over Ito in view of the AAPA and further in view of Miyazaki et al. (US 5,018,033) (hereinafter "Miyazaki").

Claims 5, 10, 11, 14 and 15 were rejected under 35 USC 103(a) as being unpatentable over Ito in view of Chun et al. (US 6,525,405) (hereinafter "Chun").

Claims 12 and 13 were rejected under 35 USC 103(a) as being unpatentable over Ito in view of Chun and further in view of the AAPA.

Claim 1

Claim 1 recites: "...a plurality of lands provided on the main board, directly connected to the second leads..." Support for this amendment may be found in at least paragraphs [0020] – [0022] of the specification and Figure 2. In the Office Action, in the "Response to Arguments" section, the Examiner notes that in its previous form, claim 1 did not distinguish over the AAPA because leads only needed to be electrically connected, rather than directly connected. Claim 1 has been amended to recite that the lands provided on the main board are **directly** connected to the second leads.

In contrast to claim 1, the AAPA discusses that the leads 4 of the laser diode module 3 are electrically connected to the leads 14 of the drive chip 13 indirectly by a wiring provided on the main board 11. This technical feature of claim 1 where the main board has the lands directly connected to the second leads, and a through hole through which the laser diode module main body 21 passes, provides that in a state in which the laser diode module main body is coupled to the rear surface of the drive chip, the main board is directly coupled to the rear surface of the drive chip so that the structure may be made compact.

Withdrawal of the foregoing rejection is requested.

Claims 2-4

Amended claim 2 recites: "...a plurality of lands provided on the main board, directly connected to the second leads..." Support for this amendment may be found in at least paragraphs [0020] – [0022] of the specification and Figure 2. In the Office Action, in the "Response to Arguments" section, the Examiner notes that in their previous form, the claims did not distinguish over the AAPA because leads only needed to be electrically connected, rather than directly connected. Claim 2 has been amended to recite that the lands provided on the main board are **directly** connected to the second leads.

In contrast to claim 2, the AAPA discusses that the leads 4 of the laser diode module 3 are electrically connected to the leads 14 of the drive chip 13 indirectly by a wiring provided on the main board 11. This technical feature of claim 2 where the main board has the lands directly connected to the second leads provides that in a state in which the laser diode module main body is coupled to the rear surface of the drive chip, the main board is directly coupled to the rear surface of the drive chip so that the structure may be made compact.

Claims 3 and 4 depend on claim 2 and are therefore believed to be allowable for at least the foregoing reasons.

Withdrawal of the foregoing rejection is requested.

Claims 5 and 10-15

Amended claim 5 recites: "...a main board having a plurality of lands to which leads of the drive chip are directly connected." Support for this amendment may be found in at least original claims 11 and 13, paragraphs [0020] – [0022] of the specification and Figure 2. The Office Action relies on the AAPA to show this feature of claim 5. However, in contrast to claim 5, the AAPA discusses that the leads 4 of the laser diode module 3 are electrically connected to the leads 14 of the drive chip 13 indirectly by a wiring provided on the main board 11. This technical feature of claim 5 where the main board has lands which are directly connected to the leads of the drive chip are directly connected provides that in a state in which the laser diode module main body is coupled to the rear surface of the drive chip, the main board is directly coupled to the rear surface of the drive chip so that the structure may be made compact.

Claims 11 and 13 have been cancelled. Claims 12, 14 and 15 depend on claim 5 and are therefore believed to be allowable for at least the foregoing reasons.

Withdrawal of the foregoing rejection is requested.

CONCLUSION

There being no further outstanding objections or rejections, it is submitted that the application is in condition for allowance. An early action to that effect is courteously solicited.

Finally, if there are any formal matters remaining after this response, the Examiner is requested to telephone the undersigned to attend to these matters.

If there are any additional fees associated with filing of this Amendment, please charge the same to our Deposit Account No. 19-3935.

Respectfully submitted,

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Date: September 20, 2007

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